

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
1	BRS	0	die with op-amp and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/23 01:16		0
2	BRS	2	die with op-amp and center	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/21 16:27		0
3	BRS	11	die with op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:39		0
4	BRS	15 6	chip with op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/21 16:36		0
5	BRS	13 8	chip with follow\$5 with stress\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/21 16:37		0
6	BRS	1	chip with follow\$5 with stress\$4 with center	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:38		0
7	BRS	2	die with follow\$5 with stress\$4 with center	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:40		0
8	BRS	15 3	current near mirror with (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:04		0
9	BRS	10	current near mirror with (op-amp or op adj amp) and die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:50		0
10	BRS	18	current near mirror with (die or chip) and (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:52		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
11	BRS	13	current near mirror same (op-amp or op adj amp) same (die or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:07		0
12	BRS	6	current near mirror with (op-amp or op adj amp) same (die or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:05		0
13	BRS	5	current near mirror same (op-amp or op adj amp) same (die or chip) and offset near volt\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:08		0
14	BRS	1	die with op-amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 16:46		0
15	BRS	12	die and op-amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 16:47		0
16	BRS	22	die and op adj amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:08		0
17	BRS	19	die and op adj amp and mirror and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:02		0
18	BRS	16	die and op adj amp and mirror and stress and center	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 16:51		0
19	BRS	3	die and op adj amp and mirror and stress not (die and op adj amp and mirror and stress and center)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:04		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error D i s t i n c t i o n
20	BRS	4	die and op adj amp and current near mirror and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:05		0
21	BRS	4	stress and op adj amp and current near mirror and pack\$6 and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:06		0
22	BRS	14	stress (center or middle or inner) near die and op adj amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:09		0
23	BRS	14	(center or middle or inner) near die and op adj amp and mirror and current	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:14		0
24	BRS	48 1	(center or middle or inner) with mirror with current	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:15		0
25	BRS	29	(center or middle or inner) with mirror with current and op adj amp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:16		0
26	BRS	18	(center or middle or inner) with mirror with current and op adj amp and die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:18		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
27	BRS	2	(center or middle or inner) and mirror near current and op adj amp and die and stress\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:19		0
28	BRS	96	(substrate or wafer) with (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:18		0
29	BRS	123	(substrate or wafer or die) with (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:19		0
30	BRS	28	(substrate or wafer or die) with (op-amp or op adj amp) and (center or middle or mid adj point or inner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:25		0
31	BRS	4	(substrate or wafer or die) with (op-amp or op adj amp) and current near mirror and (center or middle or mid adj point or inner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:28		0
32	BRS	22	(substrate or wafer or die) with (op-amp or op adj amp) and current near mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:41		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
33	BRS	7	("3477031" "3714527" "3729660" "3823354" "3863331" "3995304" "4025941") .PN.	USPAT	2004/07/23 22:39			0
34	BRS	1	(substrate or wafer or die) near (op-amp or op adj amp) and current near mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:43			0
35	BRS	8	(substrate or wafer or die) with (op-amp or op adj amp) and current near mirror and input adj offset	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:47			0
36	BRS	0	(substrate or wafer or die) and (op-amp or op adj amp) and current near mirror and input adj offset and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 23:00			0
37	BRS	15	(substrate or wafer or die) and (op-amp or op adj amp) and input adj offset and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:48			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Description
38	BRS	14	(substrate or wafer or die) and current near mirror and input near offset near volt\$6 and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 23:34		0
39	BRS	3	6104231.URPN.	USPAT	2004/07/23 23:30		0
40	BRS	10	("3882725" "3895221" "3944920" "4371837" "4521727" "4734594" "4760285" "4857842" "5055768" "5159277").PN.	USPAT	2004/07/23 23:31		0
41	BRS	18	(substrate or wafer or die or chip) and current near mirror with stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 23:35		0
42	BRS	15	(substrate or wafer or die or chip) and current near mirror with stress and amplifier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 00:14		0
43	BRS	2	(substrate or wafer or die or chip) with current near mirror with (cent\$6 or mid\$6) and amplifier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:15		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Condition	Error Info
44	BRS	17	(substrate or wafer or die or chip) with amplifier with circuit and current near mirror with (cent\$6 or mid\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:11			0
45	BRS	7	(substrate or wafer or die or chip) with (operational adj amplifier or op-amp or op adj amp) with circuit and current near mirror with (cent\$6 or mid\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:12			0
46	BRS	7	(substrate or wafer or die or chip) with (operational adj amplifier or op-amp or op adj amp) with circuit and current near mirror with (cent\$6 or mid\$6) and (integrat\$6 or monolith\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 16:50			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
47	BRS	15	(substrate or wafer or die or chip) with (operational adj amplifier or op-amp or op adj amp) with circuit and current adj mirror near input and (integrat\$6 or monolith\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 16:52		0
48	BRS	1	5623232.URPN.	USPAT	2004/07/24 17:01		0
49	BRS	2	die with stress and op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:42		0
50	BRS	4	5777465.URPN.	IBM_TDB USPAT	2004/07/24 18:42		0
51	BRS	28	substrate with stress and op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:43		0
52	BRS	4	substrate with stress and op-amp and mirror near current	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 18:46		0
53	BRS	58 82	op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:46		0
54	BRS	34	(438/\$3).ccls. and op-amp	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:50		0
55	BRS	10	(438/\$3).ccls. and op-amp and stress	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:51		0

IBM_TDB